Q	4	ω	N .		
Ø	×	⊠	⊠	Ø	
US A	US A	US B1	A A	A S	Dog
535	520	638	592	562	l un
US 5356949 A	US 5208188 A	US 6353268 B1	⊠ US 5943557 A	⊠ US 5629559 A	1 Document ID
49	88		57	56	
199	198	20020305 8	190	199	
)41(	)30	)20;	990	970;	Issue Date
018	504	305	19990824	19970513 27	6 6
19941018 10	19930504 12	<b>o</b>	တ	27	Page s
					ge
Adh com poly	Process for n multilayer lea assembly for circuit structu multilayer into die package t	Semicond attachmer apparatus	Met atta die	Packa, device	
nesi npri:	ces tilay tilay eml eml eml eml	nicc chr ara	hoc chii	ice Kac	
ve o sing	s fo /er oly : stru stru stru stru	andu nen tus	an ng a n lea	je fo	
on (m	r m lead for a ctur ctur inte	t m	d so	or s	Title
leth	Process for making multilayer lead fram assembly for an intecture and circuit structure and multilayer integrated die package formed such process	Semiconductor die attachment methoc apparatus	Method and structuattaching a semicodie to a lead frame	em.	e
Adhesive composition comprising (meth)acry polymer and epoxy re	Process for making a multilayer lead frame assembly for an integracircuit structure and multilayer integrated cil multilayer formed by such process	Semiconductor die attachment method and apparatus	ture	ဝို	
Adhesive composition comprising (meth)acrylate polymer and epoxy resin	Process for making a multilayer lead frame assembly for an integrated circuit structure and multilayer integrated circuit die package formed by such process	and	Method and structure for attaching a semiconductor die to a lead frame	lduc	
	ed uit		I	Package for semiconductor 257/666 device	
522/102	156	257/796	438/118	257	Current
/10:	56/310	/79	71	/66	ren
Ν .	0	σ σ	Φ	6	t OR
ຽງ ຽງ ຽງ	4221	9994	4.4	22 22 22	<b>フ</b>
522/103; 522/109; 525/112	156/273.9; 257/668; 257/675; 438/118	257/673; 257/676; 257/783; 438/118	438/119; 438/123	257/691; 257/692; 257/700	× c
103 109 112	273 668 675	573 576 576 783	119 123	391 392 700	Current XRef
	 		<b>J</b> .	<b>.</b>	
					_ R
					etrieva Classif
					Retrieval Classif
의 중	Z	<u>a</u> C	S	Z	
omi	ewr	obb	Moden, Walter L	iyah	
yan	nan	ley,	n, /	nare	
ัล,	, 고	C <sub>r</sub>	Val	بر ح	Inventor
<b>M</b> ik	obe	ad	ler l	enic	tor
Komiyama, Mikio et al.	Newman, Robert A.	Cobbley, Chad A. et al.	!	Miyahara, Kenichiro	
-	•			)	